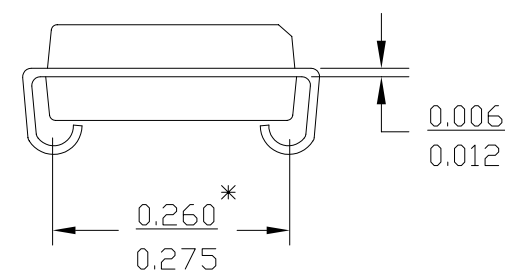
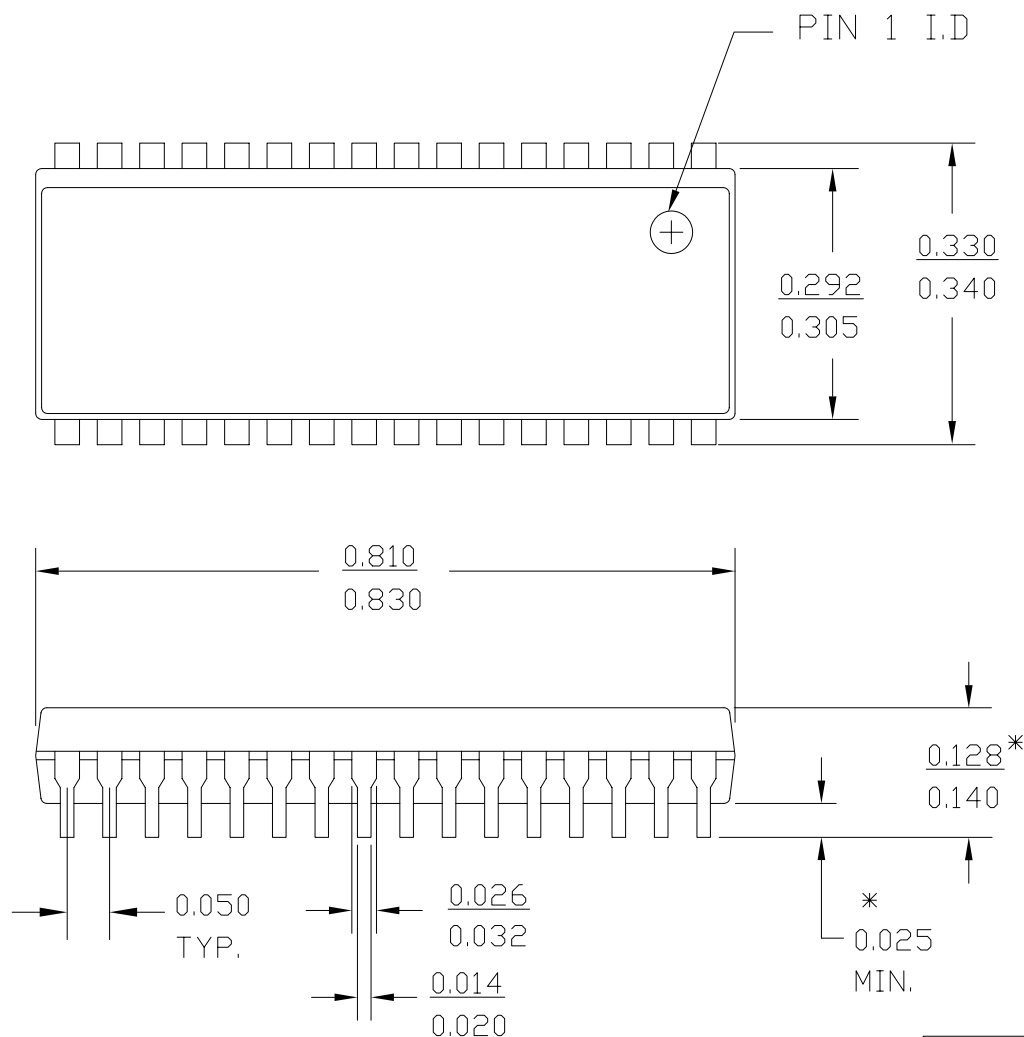



32 Lead (300 MIL) Molded SOJ

REVISIONS						
PAGE	ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED
1	-	**	456	NEW RELEASE	12/10/92	N/A
1	-	*A	45899	CHG. DIM. AT *. ADD LEAD COPLANARITY	09/11/96	N/A
1	-	*B	2871406	Changed template, & title from CATALOG 32.3 MOLDED SOJ to PACKAGE OUTLINE, 32L SOJ 300 MILS V32.3 (CATALOG 32.3 MOLDED SOJ)	02/02/10	QAD

DIMENSIONS IN INCHES MIN.
MAX.
LEAD COPLANARITY 0.004 MAX.



THIS DRAWING CONTAINS INFORMATION WHICH IS THE PROPRIETARY PROPERTY OF CYPRESS SEMICONDUCTOR CORPORATION. THIS DRAWING IS RECEIVED IN CONFIDENCE AND ITS CONTENTS MAY NOT BE DISCLOSED WITHOUT WRITTEN CONSENT OF CYPRESS SEMICONDUCTOR CORPORATION.

UNLESS OTHERWISE SPECIFIED ALL DIMENSIONS ARE IN MILLIMETERS STANDARD TOLERANCES ON: DECIMALS .XX ± 0.05 .XXX ± .XXXX + ANGLES ± 1°		DESIGNED BY HTN	DATE 09/10/96	 CYPRESS Company Confidential	
		DRAWN BY HTN	DATE 09/10/96		
		CHECKED BY TSV	DATE 02/02/10		
		APPROVED BY QAD	DATE 02/02/10		
MATERIAL N/A		APPROVED BY JGUA	DATE 02/02/10	TITLE PACKAGE OUTLINE, 32L SOJ 300 MILS V32.3 (CATALOG 32.3 MOLDED SOJ)	
FINISH N/A		APPROVED BY N/A	DATE N/A	SIZE A	PART NO. V32.3 DWG NO 51-85041 REV *B
		SCALED TO FIT		N/A	SHEET 1 OF 1